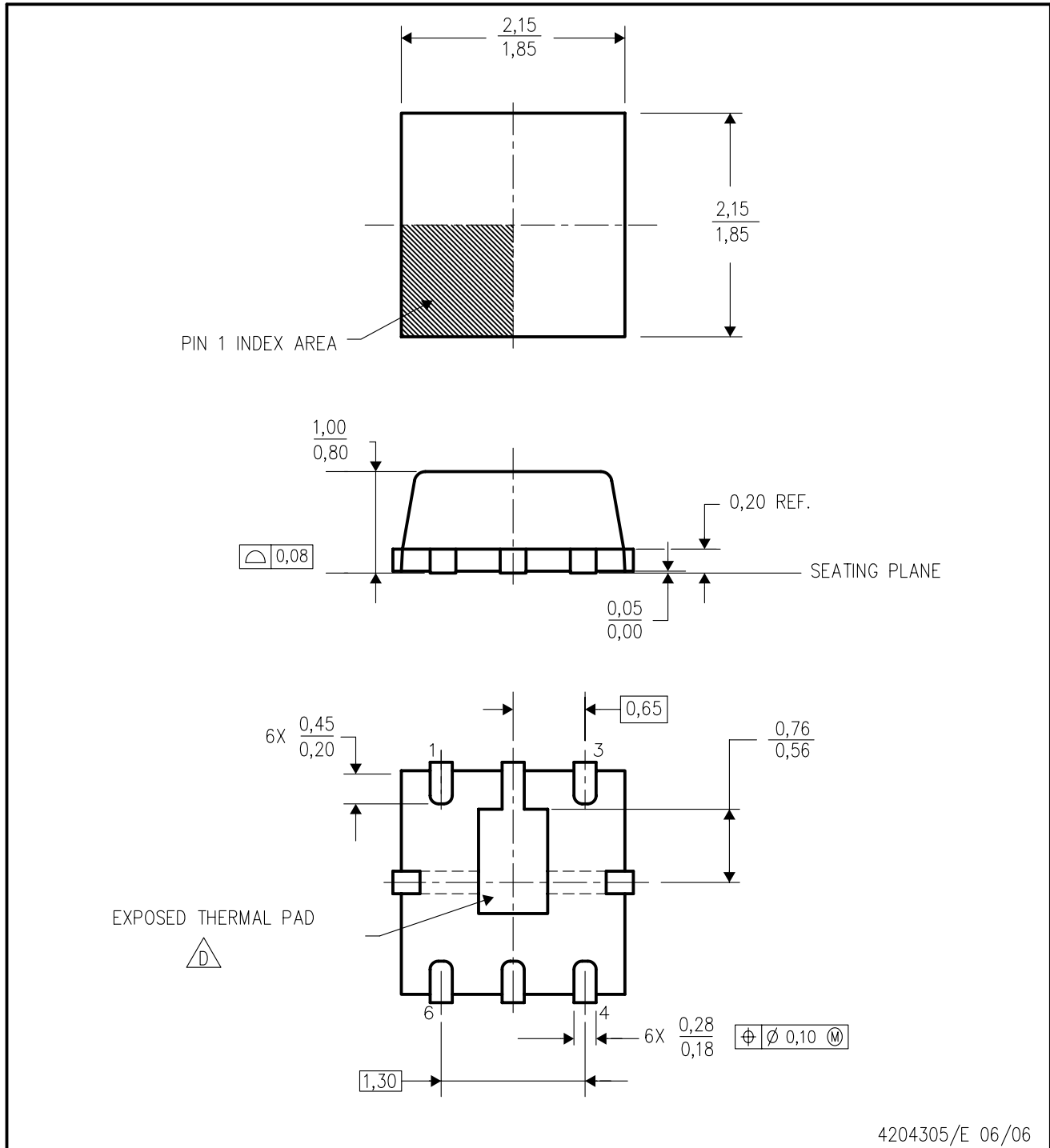



DRD (S-PDSO-N6)

PLASTIC SMALL OUTLINE



4204305/E 06/06

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Small Outline No-Lead (SON) package configuration.
-  The package thermal pad must be soldered to the board for thermal and mechanical performance. See the Product Data Sheet for details regarding the exposed thermal pad dimensions.

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Mailing Address: Texas Instruments
Post Office Box 655303 Dallas, Texas 75265

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